

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L7	394	((semiconductor or wafer or substrate)) and ((wash\$3 or rins\$3 or process\$3 or clean\$3 or etch\$3) with (liquid or fluid)) and (chamber or container or vessel or tank) and (hold\$3 or chuck\$3 or rotor or secur\$3 or support\$3) and ((nozzle or orifice or spray\$3) with (fan or plane or planar)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 15:25
L10	114	9 and (rotor or nozzle)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 14:36
S82	246	(yuji near2 kamikawa).in. or (koji near2 egashira).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 14:35
L9	248	(yuji near2 kamikawa).in. or (koji near2 egashira).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 14:35
L6	874	((semiconductor or wafer or substrate)) and (wash\$3 or rins\$3 or process\$3 or clean\$3 or etch\$3) and (chamber or container or vessel or tank) and (hold\$3 or chuck\$3 or rotor or secur\$3 or support\$3) and ((nozzle or orifice or spray\$3) with (fan or plane or planar)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 11:39
L5	947	((semiconductor or wafer or substrate)) and (chamber or container or vessel or tank) and (hold\$3 or chuck\$3 or rotor or secur\$3 or support\$3) and ((nozzle or orifice or spray\$3) with (fan or plane or planar)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 11:39
L4	1084	((semiconductor or wafer or substrate)) and (chamber or container or vessel or tank) and ((nozzle or orifice or spray\$3) with (fan or plane or planar)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 11:37

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L3	1567	((semiconductor or wafer or substrate)) and ((nozzle or orifice or spray\$3) with (fan or plane or planar)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 11:36
S79	7829	((semiconductor or wafer or substrate)) and ((nozzle or orifice or spray\$3) with (fan or plane or planar))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 11:33
L2	471	134/198-200.ccls. and (semiconductor or wafer or substrate or workpiece)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 11:30
S94	342	((134/198,199,200,902.ccls. or 216/2,92.ccls.) or 156/345.21, 345.51,345.54,345.55.ccls.) and @pd>"20050628")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 11:29
L1	158	134/200.ccls. and (semiconductor or wafer or substrate or workpiece)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 11:29
S95	1	((yuji near2 kamikawa).in. or (koji near2 egashira).in.) and @pd>"20050628"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 16:23
S86	5	((yuji near2 kamikawa).in. or (koji near2 egashira).in.) and @pd>"20041214"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 16:23
S31	364	((134/198,199,200,902.ccls. or 216/2,92.ccls.) or 156/345.21, 345.51,345.54,345.55.ccls.) and @pd>"20020926") and (semiconductor or wafer or substrate)) and ((nozzle or spray\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 16:22